

X0101

N-Channel Enhancement Mode MOSFET

60V(VDS) / ± 25 V(VGS) / 55A(ID)

Rev0.1



Wafer Specification

1. Order Information

Part No.	Description	Gross die / per 8" wafer
X0101	60V(V_{DS}) / $\pm 25V(V_{GS})$ / 55A(I_D) N-Channel Enhancement Mode MOSFET	8,441

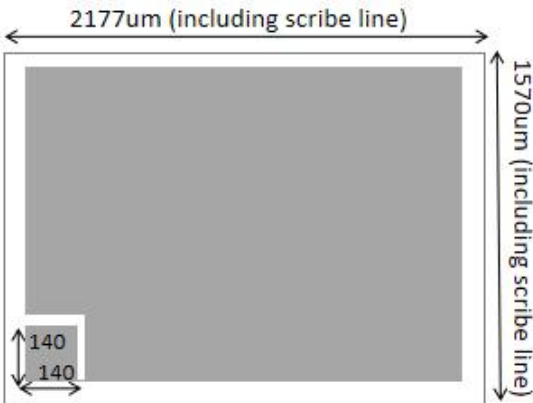
2. Mechanical Data

Nominal Back Metal Composition, Thickness	Ti-Ni-Ag (13kÅ°)
Nominal Front Metal Composition, Thickness	AlCu (4µm)
Wafer Diameter	200mm, with Ø10 notch
Wafer Thickness	150±10µm
Scribe Line Width	60µm
Passivation	SRO+SiN

3. Key Electrical Characteristics of Die (at $T_J = 25^\circ\text{C}$, unless otherwise specified)

Parameter	Description	Min.	Typ.	Max.	Unit	Test Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	60			V	$V_{GS}=0V$, $I_D=250\mu A$
I_D (Device Ref)	Continuous Drain Current			55	A	$T_J=25^\circ\text{C}$
$R_{DS(on)}(CP)$	Static Drain-to-Source On-Resistance		9.5	19	mΩ	$V_{GS}=10V$, $I_D=1A$
$R_{DS(on)}(FT)$	Static Drain-to-Source On-Resistance		8.3	11	mΩ	$V_{GS}=10V$, $I_D=30A$
$V_{GS(th)}$	Gate Threshold Voltage	2	3	4	V	$V_{DS}=V_{GS}$, $I_D=250\mu A$
I_{DSS}	Drain-to-Source Leakage Current			1	µA	$V_{DS}=60V$, $V_{GS}=0V$
I_{GSS}	Gate-to-Source Leakage Current			±100	nA	$V_{GS}=\pm 25V$, $V_{DS}=0V$
T_J , T_{STG}	Operating and Storage Temperature	-55°C to 150°C Max				

4. Die Outline

	Die Size: 2177µm × 1570µm (including scribe line)
	Gate: 140µm × 140µm
	For TO-252 package Suggest Bonding wire: Gate: 1 × 1.65 mil Cu Source: 2 × 15 mil Al